

RELIABILITY REPORT  
FOR  
MAX803TEXR+  
PLASTIC ENCAPSULATED DEVICES

September 29, 2009

**MAXIM INTEGRATED PRODUCTS**

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<b>Approved by</b>
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## Conclusion

The MAX803TEXR+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX803/MAX809/MAX810 are microprocessor ( $\mu$ P) supervisory circuits used to monitor the power supplies in  $\mu$ P and digital systems. They provide excellent circuit reliability and low cost by eliminating external components and adjustments when used with +5V, +3.3V, +3.0V, or +2.5V powered circuits. These circuits perform a single function: they assert a reset signal whenever the VCC supply voltage declines below a preset threshold, keeping it asserted for at least 140ms after VCC has risen above the reset threshold. Reset thresholds suitable for operation with a variety of supply voltages are available. The MAX803 has an open-drain output stage, while the MAX809/MAX810 have push-pull outputs. The MAX803's open-drain active-low RESET output requires a pull-up resistor that can be connected to a voltage higher than VCC. The MAX803/MAX809 have an active-low RESET output, while the MAX810 has an active-high RESET output. The reset comparator is designed to ignore fast transients on VCC, and the outputs are guaranteed to be in the correct logic state for VCC down to 1V. Low supply current makes the MAX803/MAX809/MAX810 ideal for use in portable equipment. The MAX803 is available in a 3-pin SC70 package, and the MAX809/MAX810 are available in 3-pin SC70 or SOT23 packages.

## II. Manufacturing Information

A. Description/Function:	3-Pin Microprocessor Reset Circuits
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	California or Texas
E. Assembly Location:	Malaysia
F. Date of Initial Production:	January 20, 2000

## III. Packaging Information

A. Package Type:	3-pin SC70
B. Lead Frame:	Alloy42
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0082
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	340°C/W
K. Single Layer Theta Jc:	115°C/W

## IV. Die Information

A. Dimensions:	30 X 30 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

**V. Quality Assurance Information**

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

**VI. Reliability Evaluation**

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 160 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 6.7 \times 10^{-9}$$

$$\lambda = 6.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The MS42-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX803TEXR+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	160	0
<b>Moisture Testing</b> (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data